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DATE: Tuesday, December 13, 2005

Hide?	Set Name	Query	Hit Count
		<i>DB=PGPB,USPT,EPAB,JPAB,DWPI; THES=ASSIGNEE; PLUR=YES; OP=ADJ</i>	
<input type="checkbox"/>	L1	264/297.2.ccls. and (tub\$4 or pipe).clm.	17
<input type="checkbox"/>	L2	264/297.2.ccls. and (tub\$4 or pipe or sleeve or conduit or lumen).clm.	37
<input type="checkbox"/>	L3	L2 and (anneal\$4 or heat treat\$4).clm.	0
<input type="checkbox"/>	L4	L2 and (anneal\$4).clm.	0
<input type="checkbox"/>	L5	264/346.ccls.	703
<input type="checkbox"/>	L6	L5 and (pipe or tub\$4 or lumen or conduit or sleeve).clm.	47
<input type="checkbox"/>	L7	L6 and anneal\$4	19
<input type="checkbox"/>	L8	L6 and anneal\$4.clm.	17

END OF SEARCH HISTORY

Day : Tuesday
Date: 12/13/2005

Time: 10:54:34



PALM INTRANET

Inventor Name Search Result

Your Search was:

Last Name = IIZUKA

First Name = MUNENORI

Application#	Patent#	Status	Date Filed	Title	Inventor Name
<u>08760962</u>	<u>5908578</u>	150	12/05/1996	BONDED MAGNET-FORMING COMPOSITION AND MAGNET ROLLER USING THE SAME	IIZUKA, MUNENORI
<u>09280851</u>	<u>6132634</u>	250	03/30/1999	BONDED MAGNET-FORMING COMPOSITION AND MAGNET ROLLER USING THE SAME	IIZUKA, MUNENORI
<u>09382632</u>	<u>6402977</u>	150	08/25/1999	COMPOSITION FOR RESIN MAGNET, MAGNETIC MEMBER USING SAME AND PROCESS FOR PRODUCING SAID MAGNETIC MEMBERS	IIZUKA, MUNENORI
<u>09385041</u>	<u>6221547</u>	150	08/30/1999	ELECTRICALLY CONDUCTIVE RESIN COMPOSITION AND PHOTSENSITIVE DRUM MADE THEREWITH	IIZUKA, MUNENORI
<u>09748215</u>	Not Issued	161	12/27/2000	Resin pipe, production thereof, base for photosensitive drums, and photosensitive drum constructed from said base	IIZUKA, MUNENORI
<u>09748392</u>	Not Issued	161	12/27/2000	Mixed resin compound, resin pipe, production of resin pipe, and photosensitive drum	IIZUKA, MUNENORI
<u>09905879</u>	<u>6936389</u>	150	07/17/2001	BASE BODY FOR PHOTSENSITIVE DRUM AND PHOTSENSITIVE DRUM	IIZUKA, MUNENORI
<u>09988283</u>	Not Issued	161	11/19/2001	Base body for photosensitive drum and photosensitive drum using the same	IIZUKA, MUNENORI
<u>10120370</u>	<u>6699550</u>	150	04/12/2002	BASE-BODY FOR PHOTSENSITIVE DRUM	IIZUKA, MUNENORI

				AND PHOTOSENSITIVE DRUM WITH THE USE OF THE SAME	
<u>10474767</u>	Not Issued	161	10/10/2003	Production method for photosensitive drum-use substrate and photosensitive drum-use substrate	IIZUKA, MUNENORI
<u>10478658</u>	Not Issued	161	11/25/2003	Base for photosensitive drum composed of resin composition and photosensitive drum using the same	IIZUKA, MUNENORI
<u>10540559</u>	Not Issued	19	01/01/0001	Conductive resin composition, base for photosensitive drum using the composition, and photosensitive drum	IIZUKA, MUNENORI
<u>10542382</u>	Not Issued	20	07/14/2005	Method for producing carbon fiber, catalyst structure and membrane electrode junction body for solid polymer fuel cell	IIZUKA, MUNENORI
<u>10690504</u>	Not Issued	30	10/23/2003	Mixed resin compound, resin pipe, production of resin pipe, and photosensitive drum	IIZUKA, MUNENORI

Inventor Search Completed: No Records to Display.

Search Another: Inventor	Last Name	First Name	
	<input type="text" value="iizuka"/>	<input type="text" value="munenori"/>	

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Day : Tuesday
Date: 12/13/2005



Time: 10:55:18

Inventor Name Search Result

Your Search was:

Last Name = MACHIDA

First Name = KUNIO

Application#	Patent#	Status	Date Filed	Title	Inventor Name
06780540	Not Issued	161	09/26/1985	RACKET FRAME MADE OF SYNTHETIC RESIN	MACHIDA, KUNIO
06844401	Not Issued	166	03/26/1986	RACKETS	MACHIDA, KUNIO
06880269	4713686	150	06/30/1986	HIGH SPEED INSTANTANEOUS MULTI-IMAGE RECORDER	MACHIDA, KUNIO
07117407	Not Issued	161	10/29/1987	RACKETS	MACHIDA, KUNIO
07744694	Not Issued	166	08/13/1991	RESIN WHEEL	MACHIDA, KUNIO
07813658	Not Issued	166	12/27/1991	RESIN WHEEL	MACHIDA, KUNIO
07896875	5277479	150	06/10/1992	ONE PIECE TYPE RESIN WHEEL	MACHIDA, KUNIO
07899590	5234259	250	06/18/1992	RESIN WHEEL WITH MORE THAN TWO INDEPENDENTLY MOLDED PARTS	MACHIDA, KUNIO
07901781	5282673	150	06/22/1992	COMPOUND RESIN WHEEL	MACHIDA, KUNIO
08760962	5908578	150	12/05/1996	BONDED MAGNET-FORMING COMPOSITION AND MAGNET ROLLER USING THE SAME	MACHIDA, KUNIO
08808436	Not Issued	161	02/28/1997	VIBRATION-PROOF BOSS	MACHIDA, KUNIO
08963359	5922250	150	11/03/1997	METHOD OF MANUFACTURING OPTICAL-USE PLASTIC PRODUCTS	MACHIDA, KUNIO
09032833	6083433	150	03/02/1998	CLEANING BLADE AND PROCESS FOR PRODUCING SAME	MACHIDA, KUNIO
09181924	6383436	150	10/29/1998	PROCESS FOR PRODUCING	MACHIDA, KUNIO

				INK-JET PRINTER MEMBER	
<u>09185599</u>	<u>5991574</u>	150	11/04/1998	PHOTOSENSITIVE DRUM	MACHIDA, KUNIO
<u>09280851</u>	<u>6132634</u>	250	03/30/1999	BONDED MAGNET-FORMING COMPOSITION AND MAGNET ROLLER USING THE SAME	MACHIDA, KUNIO
<u>09330064</u>	<u>6394137</u>	150	06/11/1999	FLUID SUPPLY VALVE	MACHIDA, KUNIO
<u>09385041</u>	<u>6221547</u>	150	08/30/1999	ELECTRICALLY CONDUCTIVE RESIN COMPOSITION AND PHOTOSENSITIVE DRUM MADE THEREWITH	MACHIDA, KUNIO
<u>09427984</u>	<u>6505839</u>	150	10/27/1999	GASKETED COVER, COVER FOR ELECTRONIC EQUIPMENT AND PROCESS FOR PRODUCING THE COVERS	MACHIDA, KUNIO
<u>09501239</u>	Not Issued	161	02/10/2000	Gasket and process for producing the same	MACHIDA, KUNIO
<u>09503473</u>	Not Issued	161	02/14/2000	Gasket fitted to frame and process for producing the same	MACHIDA, KUNIO
<u>09505683</u>	<u>6399696</u>	150	02/17/2000	THERMOPLASTIC ELASTOMER COMPOSITION AND GASKET MATERIAL	MACHIDA, KUNIO
<u>09543353</u>	Not Issued	161	04/05/2000	Gasket fitted to frame and process for producing the same	MACHIDA, KUNIO
<u>09671170</u>	<u>6663975</u>	150	09/28/2000	RESIN COMPOSITION AND GASKET MATERIAL	MACHIDA, KUNIO
<u>09748215</u>	Not Issued	161	12/27/2000	Resin pipe, production thereof, base for photosensitive drums, and photosensitive drum constructed from said base	MACHIDA, KUNIO
<u>09748392</u>	Not Issued	161	12/27/2000	Mixed resin compound, resin pipe, production of resin pipe, and photosensitive drum	MACHIDA, KUNIO
<u>09905879</u>	<u>6936389</u>	150	07/17/2001	BASE BODY FOR PHOTOSENSITIVE DRUM AND PHOTOSENSITIVE DRUM	MACHIDA, KUNIO
<u>09908573</u>	<u>6550498</u>	150	07/20/2001	FLUID SUPPLY VALVE	MACHIDA, KUNIO
<u>09988283</u>	Not Issued	161	11/19/2001	Base body for photosensitive drum and photosensitive drum using the same	MACHIDA, KUNIO

10015785	Not Issued	161	12/17/2001	Gasketed cover, cover for electronic equipment and process for producing the covers	MACHIDA, KUNIO
10098341	Not Issued	132	03/18/2002	Ink-jet printer member	MACHIDA, KUNIO
10098542	Not Issued	93	03/18/2002	PROCESS FOR PRODUCING INK-JET MEMBER	MACHIDA, KUNIO
10120370	6699550	150	04/12/2002	BASE-BODY FOR PHOTSENSITIVE DRUM AND PHOTSENSITIVE DRUM WITH THE USE OF THE SAME	MACHIDA, KUNIO
10359149	6748979	150	02/06/2003	FLUID SUPPLY VALVE	MACHIDA, KUNIO
10474767	Not Issued	161	10/10/2003	Production method for photosensitive drum-use substrate and photosensitive drum-use substrate	MACHIDA, KUNIO
10478658	Not Issued	161	11/25/2003	Base for photosensitive drum composed of resin composition and photosensitive drum using the same	MACHIDA, KUNIO
10690504	Not Issued	30	10/23/2003	Mixed resin compound, resin pipe, production of resin pipe, and photosensitive drum	MACHIDA, KUNIO

Inventor Search Completed: No Records to Display.

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	<input type="text" value="machida"/>	<input type="text" value="kunio"/>	

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Day : Tuesday
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**PALM INTRANET****Application Number Information**

Application Number: 09/748392

Examiner Number: 62263 / WOODWARD, ANA**Assignments**

Filing or 371(c) Date: 12/27/2000

Group Art Unit: 1711

IFW IMAGE

Effective Date: 12/27/2000

Class/Subclass: 525/178.000

Application Received: 12/27/2000

Lost Case: NO

Pat. Num./Pub. Num: /20020037465

Interference Number:

Issue Date: 00/00/0000

Unmatched Petition: NO

Date of Abandonment: 12/09/2003

L&R Code: Secrecy Code:1

Attorney Docket Number: Q62487

Third Level Review: NO

Secrecy Order: NO

Status: 161 /ABANDONED -- FAILURE TO RESPOND TO AN
OFFICE ACTION

Status Date: 03/29/2004

Confirmation Number: 3771

Oral Hearing: NO

Title of Invention: MIXED RESIN COMPOUND, RESIN PIPE, PRODUCTION OF RESIN
PIPE, AND PHOTSENSITIVE DRUM

Bar Code	PALM Location	Location Date	Charge to Loc	Charge to Name	Employee Name	Location
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L6: Entry 2 of 2

File: PGPB

Mar 28, 2002

PGPUB-DOCUMENT-NUMBER: 20020037465
PGPUB-FILING-TYPE: new
DOCUMENT-IDENTIFIER: US 20020037465 A1

TITLE: Mixed resin compound, resin pipe, production of resin pipe, and
photosensitive drum

PUBLICATION-DATE: March 28, 2002

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY
Iizuka, Munenori	Tokyo		JP
<u>Machida</u> , Kunio	Tokyo		JP

APPL-NO: 09/748392 [\[PALM\]](#)
DATE FILED: December 27, 2000

FOREIGN-APPL-PRIORITY-DATA:

COUNTRY	APPL-NO	DOC-ID	APPL-DATE
JP	11-369777	1999JP-11-369777	December 27, 1999
JP	11-369778	1999JP-11-369778	December 27, 1999
JP	11-369779	1999JP-11-369779	December 27, 1999
JP	11-369780	1999JP-11-369780	December 27, 1999
JP	11-369781	1999JP-11-369781	December 27, 1999
JP	11-369782	1999JP-11-369782	December 27, 1999
JP	11-369783	1999JP-11-369783	December 27, 1999
JP	11-369784	1999JP-11-369784	December 27, 1999

INT-CL: [07] [G03 G 5/10](#), [C08 K 3/04](#), [C08 K 3/08](#)

US-CL-PUBLISHED: 430/69; 430/127, 524/495, 524/440
US-CL-CURRENT: [430/69](#); [430/127](#), [524/440](#), [524/495](#)

REPRESENTATIVE-FIGURES: NONE

ABSTRACT:

Disclosed herein are a mixed resin compound, a resin pipe, a process for producing said resin pipe, and a photosensitive drum. The resin compound meets at least one of the following requirements. It is a mixture of two or more kinds of resins blended in a specific manner, it undergoes annealing under specific conditions, and it has specific values of surface roughness, Vickers hardness, coefficient of linear expansion, flexural modulus, and thermal conductivity. The resin pipe is

suitable for use as the cylindrical base of the photosensitive drum for electrophotographic machines, such as copying machines, facsimiles, and printers. It is superior in surface smoothness, dimensional stability, coatability, and handlability, and hence it is very little vulnerable to damage during handling and dimensional change due to resin shrinkage and is; superior in heat resistance (desirable for solvent removal) and mechanical strength (desirable for flange fitting).

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L6: Entry 2 of 2

File: PGPB

Mar 28, 2002

PGPUB-DOCUMENT-NUMBER: 20020037465
PGPUB-FILING-TYPE: new
DOCUMENT-IDENTIFIER: US 20020037465 A1

TITLE: Mixed resin compound, resin pipe, production of resin pipe, and
photosensitive drum

PUBLICATION-DATE: March 28, 2002

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY
Iizuka, Munenori	Tokyo		JP
<u>Machida</u> , Kunio	Tokyo		JP

US-CL-CURRENT: [430/69](#); [430/127](#), [524/440](#), [524/495](#)

CLAIMS:

1. A mixed resin compound in a desired shape formed by injection molding from a molding material containing a mixed resin composed of two or more kinds of resins differing in the rate of crystallization, wherein said resins are mixed in pellet form and the resulting mixture of pellets is injection-molded as such.
2. The mixed resin compound as defined in claim 1, wherein said mixed resin comprises (A) at least one resin component selected from a polyamide resin obtained from metaxylylenediamine and adipic acid, a polyamide resin obtained from .epsilon.-caprolactam, and an alloy resin obtained by blending a polyamide resin with a resin having a water absorption no higher than 0.3%, and (B) at least one of the other resins.
3. The mixed resin compound as defined in claim 1, which contains an electrically conducting material dispersed therein.
4. The mixed resin compound as defined in claim 3, which contains carbon black as the electrically conducting material.
5. The mixed resin compound as defined in claim 4, which contains the carbon black in an amount of 5-30 weight %.
6. The mixed resin compound as defined in claim 1, which contains a reinforcing inorganic filler.
7. The mixed resin compound as defined in claim 6, which contains the reinforcing inorganic filler in an amount of 1-30 weight %.
8. A photosensitive drum consisting of a cylindrical base and a photosensitive

layer formed on the outer surface thereof, wherein the cylindrical base is formed from the mixed resin compound as defined in claim 1.

9. A process for producing a resin pipe by injection molding from a thermoplastic resin or a resin compound based on said thermoplastic resin, wherein the molded product undergoes annealing after demolding.

10. A process for producing a resin pipe as defined in claim 9, wherein the resin compound contains at least one resin component selected from a polyamide resin obtained from metaxylylenediamine and adipic acid, a polyamide resin obtained from .epsilon.-caprolactam, and an alloy resin obtained by blending a polyamide resin with a resin having a water absorption no higher than 0.3%.

11. A process for producing a resin pipe as defined in claim 9, wherein the annealing is carried out at 100-140.degree. C. for 0.5-2 hours.

12. A process for producing a resin pipe as defined in claim 9, wherein the resin pipe is an electrically conductive resin pipe formed by injection molding from an electrically conductive resin compound composed of a thermoplastic resin and an electrically conducting material dispersed therein.

13. A process for producing a resin pipe as defined in claim 12, wherein the electrically conductive resin compound contains carbon black as an electrically conducting material.

14. A process for producing a resin pipe as defined in claim 13, wherein the content of the carbon black is 5-30 weight %.

15. A process for producing a resin pipe as defined in claim 9, wherein the electrically conductive resin compound is one which contains a reinforcing inorganic filler dispersed therein.

16. A process for producing a resin pipe as defined in claim 15, wherein the content of the reinforcing inorganic filler is 1-30 weight %.

17. A process for producing a resin pipe as defined in claim 9, wherein the resin pipe is a base for a photosensitive drum.

18. A photosensitive drum consisting of a cylindrical base of electrically conductive resin compound and a photosensitive layer formed by coating on the outer surface of said cylindrical base, wherein the outer surface of the cylindrical base has a surface roughness equal to or smaller than 0.2 .mu.m in terms of Ra (center line average height) and equal to or smaller than 0.8 .mu.m in terms of Rmax (maximum height).

19. A photosensitive drum as defined in claim 18, wherein the electrically conductive resin compound contains at least one resin component selected from a polyamide resin obtained from metaxylylenediamine and adipic acid, a polyamide resin obtained from .epsilon.-caprolactam, and an alloy resin obtained by blending a polyamide resin with a resin having a water absorption no higher than 0.3%.

20. A photosensitive drum as defined in claim 18, wherein the electrically conductive resin compound contains carbon black as an electrically conducting material.

21. A photosensitive drum as defined in claim 20, wherein the content of the carbon black is 5-30 weight %.

22. A process for producing a resin pipe as defined in claim 18, wherein the electrically conductive resin compound is one which contains a reinforcing inorganic filler dispersed therein.

23. A photosensitive drum as defined in claim 22, wherein the content of the reinforcing inorganic filler is 1-30 weight %.

24. A photosensitive drum consisting of a cylindrical base and a photosensitive layer formed by coating on the outer surface thereof, wherein the cylindrical base is an electrically conductive resin pipe formed from an electrically conductive resin compound which contains as a base resin having a Vickers hardness no lower than 15.

25. A photosensitive drum as defined in claim 24, wherein the base resin of the electrically conductive resin compound contains at least one resin component selected from a polyamide resin obtained from metaxylylenediamine and adipic acid, a polyamide resin obtained from .epsilon.-caprolactam, and an alloy resin obtained by blending a polyamide resin with a resin having a water absorption no higher than 0.3%.

26. A photosensitive drum as defined in claim 24, wherein the electrically conductive resin compound contains carbon black as an electrically conducting material.

27. A photosensitive drum as defined in claim 26, wherein the content of the carbon black is 5-30 weight %.

28. A photosensitive drum as defined in claim 24, wherein the electrically conductive resin compound is one which contains a reinforcing inorganic filler dispersed therein.

29. A photosensitive drum as defined in claim 28, wherein the content of the reinforcing inorganic filler is 1-30 weight %.

30. A resin pipe obtained by injection molding from a thermoplastic resin or a resin compound based on said thermoplastic resin, wherein said thermoplastic resin or the base resin for said resin compound is a resin having a coefficient of linear expansion no larger than $1.0 \times 10^{-4}/K$.

31. A resin pipe as defined in claim 30, which contains at least one resin component selected from a polyamide resin obtained from metaxylylenediamine and adipic acid, a polyamide resin obtained from .epsilon.-caprolactam, and an alloy resin obtained by blending a polyamide resin with a resin having a water absorption no higher than 0.3%.

32. A resin pipe as defined in claim 30, wherein the resin pipe is an electrically conductive resin pipe formed by injection molding from an electrically conductive resin compound composed of a thermoplastic resin and an electrically conducting material dispersed therein.

33. A resin pipe as defined in claim 32, wherein the electrically conductive resin compound contains carbon black as an electrically conducting material.

34. A resin pipe as defined in claim 33, wherein the content of the carbon black is 5-30 weight %.

35. A resin pipe as defined in claim 30, wherein the electrically conductive resin

compound is one which contains a reinforcing inorganic filler dispersed therein.

36. A resin pipe as defined in claim 35, wherein the content of the reinforcing inorganic filler is 1-30 weight %.

37. A resin pipe as defined in claim 30, wherein the resin pipe is a base for a photosensitive drum.

38. A photosensitive drum consisting of a cylindrical base and a photosensitive layer formed by coating on the outer surface thereof, wherein the cylindrical base is a resin pipe defined in claim 30.

39. A photosensitive drum consisting of a cylindrical base and a photosensitive layer formed from a solution containing a photosensitive material by coating on the outer surface thereof, wherein the cylindrical base is an electrically conductive resin pipe formed from an electrically conductive resin compound which has a flexural modulus no lower than 7×10^{10} MPa.

40. A photosensitive drum as defined in claim 39, wherein the electrically conductive resin compound contains at least one resin component selected from a polyamide resin obtained from metaxylylenediamine and adipic acid, a polyamide resin obtained from ϵ -caprolactam, and an alloy resin obtained by blending a polyamide resin with a resin having a water absorption no higher than 0.3%.

41. A photosensitive drum as defined in claim 39, wherein the electrically conductive resin compound contains carbon black as an electrically conducting material.

42. A photosensitive drum as defined in claim 41, wherein the content of the carbon black is 5-30 weight %.

43. A photosensitive drum as defined in claim 39, wherein the electrically conductive resin compound is one which contains a reinforcing inorganic filler dispersed therein.

44. A photosensitive drum as defined in claim 43, wherein the content of the reinforcing inorganic filler is 1-30 weight %.

45. A photosensitive drum made up of a resin pipe as a base, a photosensitive layer formed on the outer surface of the base, and a separately formed resin flange pressure-fitted into at least one open end of the base, wherein the resin pipe is formed from a resin material having a flexural strength no lower than 100 MPa.

46. photosensitive drum as defined in claim 45, wherein the resin material from which the resin pipe is formed is an electrically conductive resin compound containing at least one resin component selected from a polyamide resin obtained from metaxylylenediamine and adipic acid, a polyamide resin obtained from ϵ -caprolactam, and an alloy resin obtained by blending a polyamide resin with a resin having a water absorption no higher than 0.3%.

47. photosensitive drum as defined in claim 45, wherein the electrically conductive resin compound from which the resin pipe is formed contains carbon black as an electrically conducting material.

48. photosensitive drum as defined in claim 47, wherein the content of the carbon black is 5-30 weight %.

49. photosensitive drum as defined in claim 45, wherein the electrically conductive resin compound is one which contains a reinforcing inorganic filler dispersed therein.

50. photosensitive drum as defined in claim 49, wherein the content of the reinforcing inorganic filler is 1-30 weight %.

51. photosensitive drum consisting of a cylindrical base and a photosensitive layer formed on the outer surface thereof by coating and drying from a solution containing a photosensitive material, wherein the cylindrical base is an electrically conductive resin pipe formed from an electrically conductive resin having a thermal conductivity no lower than 0.2 W/m.multidot.K.

52. photosensitive drum as defined in claim 51, wherein the electrically conductive resin compound contains at least one resin component selected from a polyamide resin obtained from metaxylylenediamine and adipic acid, a polyamide resin obtained from .epsilon.-caprolactam, and an alloy resin obtained by blending a polyamide resin with a resin having a water absorption no higher than 0.3%.

53. photosensitive drum as defined in claim 51, wherein the electrically conductive resin compound contains carbon black as an electrically conducting material.

54. A photosensitive drum as defined in claim 53, wherein the content of the carbon black is 5-30 weight %.

55. A photosensitive drum as defined in claim 51, wherein the electrically conductive resin compound is one which contains a reinforcing inorganic filler dispersed therein.

56. A photosensitive drum as defined in claim 55, wherein the content of the reinforcing inorganic filler is 1-30 weight %.

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<input type="checkbox"/>	L2	L1 and anneal\$4	0
<input type="checkbox"/>	L3	machida.IN. and anneal\$4	106
<input type="checkbox"/>	L4	L3 and injection	15
<input type="checkbox"/>	L5	machida.IN. and anneal\$4.clm.	14
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<input type="checkbox"/>	L3	L2 and injection.clm.	48
<input type="checkbox"/>	L4	L2 and injection mold\$4.clm.	12

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	<i>DB=PGPB,USPT,EPAB,JPAB,DWPI; THES=ASSIGNEE; PLUR=YES; OP=ADJ</i>		
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<input type="checkbox"/>	L2	(pip\$4 or tub\$4).clm. and anneal\$4.clm.	1560
<input type="checkbox"/>	L3	L2 and injection.clm.	48
<input type="checkbox"/>	L4	L2 and injection mold\$4.clm.	12
<input type="checkbox"/>	L5	4025594.pn.	4
<input type="checkbox"/>	L6	L5 and polyamide	0
<input type="checkbox"/>	L7	L5 and amide	0
<input type="checkbox"/>	L8	L5 and resin	0
<input type="checkbox"/>	L9	L5 and filler	0
<input type="checkbox"/>	L10	L5 and carbon black	0
<input type="checkbox"/>	L11	resin pipe same injection mold\$4 same anneal\$4	6

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Refine Search

Search Results -

Term	Documents
INJECTION	940349
INJECTIONS	74703
MOLDING	591979
MOULDING	255992
PIPE	1192239
PIPES	391271
CONDUIT	354284
CONDUITS	151919
TUB\$4	0
TUB	44654
TUBA	350
(INJECTION MOLDING WITH (TUB\$4 OR PIPE OR CONDUIT) WITH ANNEAL\$4).PGPB,USPT,EPAB,JPAB,DWPI.	23

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Hit Count Set Name
result set

DB=PGPB,USPT,EPAB,JPAB,DWPI; THES=ASSIGNEE; PLUR=YES; OP=ADJ

<u>L1</u>	resin pipe with anneal\$4	11	<u>L1</u>
<u>L2</u>	(pip\$4 or tub\$4).clm. and anneal\$4.clm.	1560	<u>L2</u>
<u>L3</u>	L2 and injection.clm.	48	<u>L3</u>
<u>L4</u>	L2 and injection mold\$4.clm.	12	<u>L4</u>
<u>L5</u>	4025594.pn.	4	<u>L5</u>
<u>L6</u>	L5 and polyamide	0	<u>L6</u>
<u>L7</u>	L5 and amide	0	<u>L7</u>
<u>L8</u>	L5 and resin	0	<u>L8</u>
<u>L9</u>	L5 and filler	0	<u>L9</u>
<u>L10</u>	L5 and carbon black	0	<u>L10</u>
<u>L11</u>	resin pipe same injection mold\$4 same anneal\$4	6	<u>L11</u>
<u>L12</u>	annealing resin pipe	0	<u>L12</u>
<u>L13</u>	injection molding with (tub\$4 or pipe or conduit)	8873	<u>L13</u>
<u>L14</u>	injection molding with (tub\$4 or pipe or conduit) with anneal\$4	23	<u>L14</u>
<u>L15</u>	injection molding with (tub\$4 or pipe or conduit) with anneal\$4	23	<u>L15</u>
<u>L16</u>	injection molding with (tub\$4 or pipe or conduit) with anneal\$4	23	<u>L16</u>

END OF SEARCH HISTORY